

LINEAR TECHNOLOGY MATERIALS DECLARATION

ltc1541is8#trpbf

(Engineering Calculation)

SOIC

(printed on: 2020-07-11 19:40:04)

TOTAL MASS (g) : 0.073284

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.001960 | 1000000 | 26745.3203125 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000082 | 1000000 | 1118.93676758 | | |
| Lead Frame | A42 | Copper (Cu) | 7440-50-8 | 0.000000 | 0 | 0 | | |
| | | Iron (Fe) | 7439-89-6 | 0.014071 | 580000 | 192006.828125 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000000 | 0 | 0 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000000 | 0 | 0 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.010189 | 420000 | 139034.71875 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.024260 | 1000000 | 331041.53125 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.001477 | 1000000 | 20152.4882812 | | |
| | | External Plating Total: | | | | 0.001477 | 1000000 | 20152.4882812 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000194 | 1000000 | 2647.24072266 | | |
| Internal Plating Total: | | | | 0.000194 | 1000000 | 2647.24072266 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.000677 | 750000 | 9238.05078125 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000226 | 250000 | 3083.89916992 | | |
| Die Attach Total: | | | | 0.000903 | 1000000 | 12321.9511719 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.006633 | 150000 | 90511.078125 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.036263 | 820000 | 494829.34375 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.001106 | 25000 | 15092.0019531 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000221 | 5000 | 3015.67114258 | | |
| | | Encapsulation Total: | | | | 0.044223 | 1000000 | 603448.0625 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000185 | 1000000 | 2524.43066406 | | |
| | | | | | TOTAL MASS (g) : | 0.073284 | | |